

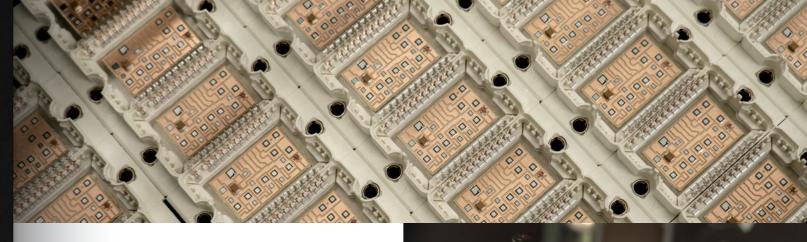
ENGINEERING TOMORROW

Danfoss Silicon Power | North America

Engineering tomorrow with world-class power modules build in the US







Standard housings with flexibility

Danfoss works with a customized business model based on a philosophy of dialogue and freedom. It allows us to give you a flexibility never before seen in the world of power modules.

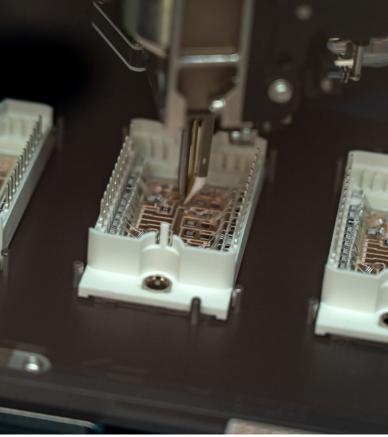
Accommodating an increased industry focus on system optimization, we offer custom solutions in standard industry packages. This allows for flexible configurations, including free choice of chip in standard housings that fit your specific application profile.

The power to trust

Danfoss has specialized in customized power modules for industrial, automotive and renewable applications for over three decades. Our power module capabilities are the result of years of research, development and testing.

Partnering with Danfoss, we help you optimize your power solution. Our highly skilled and specialized engineers work closely together with you to design power modules fitted specifically to your application. Keeping development time and overall costs down, we set you up with a solution making the most out of silicon (Si) or silicon carbide (SiC) and is scaled correctly to meet your performance targets.





Chip independence

All power modules from Danfoss are compatible with any type of semiconductor from any manufacturer of IGBTs and MOSFETs. We offer both Si and SiC configurations and we can support your specific technology and performance targets.

Danfoss is not tied to a particular manufacturer, which means we can accommodate both your first choice and your back-up provider in case of supply shortage.

Drawing on years of industry knowledge and expertise, we also help you identify the best possible chip for your application to ensure top performance and security of supply.

What we offer specifically within each industry







Battery energy storage Maximizing battery performance

- SiC for higher system efficiency and better heat dissipation
- Reduced switching losses leading to smaller power devices and increased system lifecycle
- Highest power density and power conversion efficiency
- Flexible use of SiC suppliers



PV Inverters Targeting high efficiency

- SiC for higher system energy output · Longer lifetime and reliability • Flexible use of SiC suppliers

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Automotive traction DCM[™]1000 technology platform

- Using Si and SiC to their full potential for cost-effective solutions
- Chip flexibility
- Higher power density
- Robust, reliable and longer lifetime
- Scalable across voltage classes



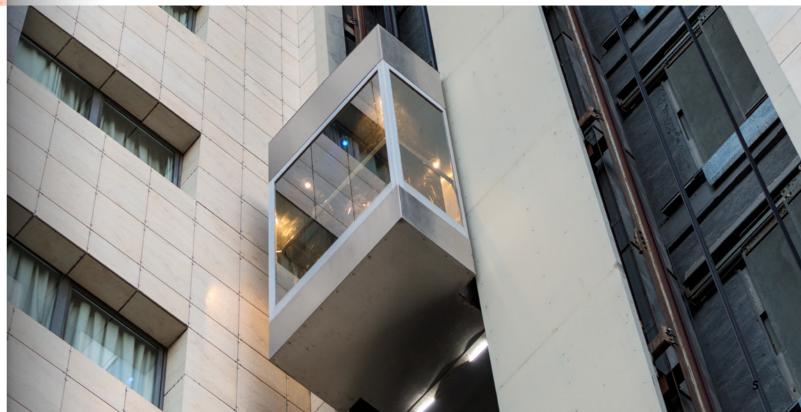
EV charging SiC for efficient DC fast charging

- SiC for higher power density and reduced footprint
- Reduced switching and
- conduction losses leading to reduced cooling effort
- Flexible use of SiC suppliers



Active Power Reliability and efficiency in focus

- Robustness and reliability
- Unmatched power conversion efficiency
- Highest power density
- Reduced number of passive components





Elevator Maximizing elevator uptime

- Higher power cycling with advanced bonding and joining technology (DBB®)
- Increased power output
- Increased lifetime
- Higher junction temperature

Leading technology portfolio

Danfoss is a front-runner in the packaging of power semiconductors. We have developed a market-leading portfolio of innovative packaging technologies that address the most challenging aspects of power electronics. These technologies equip us to develop the most reliable and cost-efficient solution for your individual application.

ShowerPower® Enabling the highest power density

Smart and efficient thermal management is an essential element to achieve higher system performance. Our patented ShowerPower® concept for direct liquid cooling of power modules offers superior thermal performance at a very low cost. This cooling design almost doubles the effective heat transfer coefficient enabling much higher current carrying capability.

Benefits

- Enables higher power density
- Increases system lifetime
- Eliminates the need for thermal interface material
- Reduces the semiconductor area needed to achieve the desired output
- More efficient than standard cooling
- Low differential pressure-drop
- Homogeneous cooling



Transfer molding For extremely robust packages

Hybrid electric, battery electric drivetrains and many applications subjected to demanding and harsh conditions benefit from our unique transfer molded packaging design. Transfer molding in combination with our bond buffer technology allows for more extreme temperature cycling and higher junction temperatures. Sealed and protected against vibrations and humidity, the power module provides stable and reliable performance even when subjected to mechanical shocks and damp environments.

Benefits

- Superior mechanical robustness
- Stable at higher operation temperatures and temperature cycles
- Protected against humidity
- Longer lifetime



Danfoss Bond Buffer® Making the most out of semiconductors

Increase power density without derating the current, while actually improving reliability and prolonging the lifetime of the module. Danfoss Bond Buffer® is a breakthrough in bonding and joining technology that helps you raise the bar for system performance. Our patented DBB® concept is an innovative combination of copper wire bonding and sintered die attach that replaces traditional solder joints. The result is a power module with high thermal robustness that significantly enhances the system performance on all essential parameters.

Benefits

- Reduces the semiconductor area for a more costeffective solution
- Increased power density and thermal robustness
- Improved lifetime and reliability



About Danfoss Silicon Power

Danfoss Silicon Power is a subsidiary of the Danfoss Group, the largest industrial company in Denmark. Danfoss employs more than 26,000 people in over 100 countries within development, production, sales and support.

For over three decades, Danfoss Silicon Power has been helping top tier manufacturers and system suppliers meet stringent reliability, design and cost tartgets by designing, developing and manufacturing customized power modules for industrial, automotive and renewable applications.

Our state-of-the-art development and production plants in Utica, New York and in Flensburg, Germany boast 9,000 m2 of cleanroom manufacturing area. It is here we design, prototype and manufacture today's and tomorrow's power solutions. Our ability to deliver large series production allows to meet the high demands of major industries.

Our research, development and production facilities in Flensburg and Utica are certified according to ISO 9001, IATF 16949, ISO 14001, ISO 50001 and OHSAS 18001. This enables us to quickly transfer development projects to high volume production that can be integrated seamlessly into our customers' supply chain with a consistent focus on quality.

Unique security of supply

Danfoss Silicon Power's global manufacturing footprint means we can offer unique supply chain support and risk mitigation, as you effectively achieve double sourcing when procuring from us.

Visit **siliconpower.danfoss.com** for further product information.

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